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S/N 09/733,289

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiao-Chun Mu et al.

Examiner: Dilinh P. Nguyen

Serial No.: 09/733,289✓

Group Art Unit: 2814

Filed: December 8, 2000✓

Docket: 884.798US1

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on July 1, 2002. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office action, thereby moving the deadline for response from October 1, 2002 to November 1, 2002.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect cancellation of claim 5, amendment of previously pending claim 1, and addition of new claim 29. The specific amendments to individual claims are detailed in the following marked up set of claims.

1. (Amended) A microelectronic package, comprising:
 - a heat sink;
 - at least one microelectronic die having an active surface and a back surface, said at least one microelectronic die back surface adjacent to said heat sink;
 - a patterned thermally conductive adhesive layer disposed between said at least one microelectronic die and said heat sink; and
 - an encapsulation material disposed on said heat sink and said microelectronic die active surface.

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